

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (currently amended) A semiconductor device comprising:

a die pad supported by a plurality of suspension leads;

a semiconductor chip disposed over the die pad;

a plurality of leads arranged around the semiconductor chip,

~~terminals connected to the plural leads respectively,~~

the plurality of leads each having a first end, a second end opposite the first end, an upper surface, a lower surface, side faces, and a terminal disposed between the first end and the second end and providing an electrical connection to a wiring substrate;

a plurality of wires electrically ~~for~~ connecting the semiconductor chip with the first ends of the plurality of leads; and ~~the plural leads electrically with each other,~~ and

a resin sealing member ~~for~~ sealing the semiconductor chip, a part of each of the plurality of leads and the plurality of ~~the plural leads and the plural wires;~~

wherein the terminals of the plurality of leads are
~~connected respectively to the plural leads being exposed~~
~~from to the exterior from~~ a back surface of the resin
sealing member₇;

wherein the upper surface, the lower surface and the
side faces of the second ends of the plurality of leads are
covered with resin of the resin sealing member;

wherein a cut face of each of the second ends of the
plurality of leads is exposed from a side face of the one
~~ends of the plural leads are exposed to the exterior from~~
~~side faces of the resin sealing member and are covered~~
~~throughout the whole peripheries thereof with resin which~~
~~constitutes the resin sealing member,~~ and

wherein one end of each of the plurality of suspension
leads is branched in a vicinity of a corner of the resin
sealing member, branched portions of said one end are
exposed to side faces of the resin sealing member, and each
branched portion has an upper surface, a lower surface, and
side faces covered by the resin sealing member.

2. (canceled)

3. (canceled)

4. (currently amended) A semiconductor device according to claim 21, wherein the plurality of suspension leads are each partially exposed ~~to the exterior~~ from thea back surface of the resin sealing member.

5. (currently amended) A semiconductor device according to claim 1, wherein the terminals are respectively constituted such that portions of the plurality of leads ~~are projectprojected to the exterior~~ from a back surface of the resin sealing member.

6. (currently amended) A semiconductor device according to claim 1, wherein the terminals are formed of an electrically conductive material different from a~~the~~ material formingof the plurality of leads.

7. (currently amended) A semiconductor device according to claim 21, wherein a back surface of the die pad portion is partially exposed to an~~the~~ exterior from a back surface of the resin sealing member.

8. (canceled)

9. (canceled)

10. (currently amended) A semiconductor device according to claim 1, wherein the terminals are arranged zigzag in two rows along ~~the~~ sides of the resin sealing member.

11. (currently amended) A semiconductor device according to claim ~~3~~1, wherein an~~the~~ area of the die pad ~~portion~~ is smaller than an~~the~~ area of the semiconductor chip.

Claims 12-15 (canceled)